

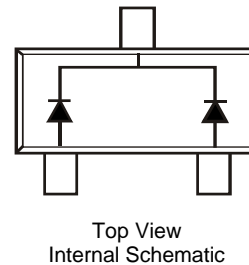
Features

- Fast Switching Speed
- Surface-Mount Package Ideally Suited for Automated Insertion
- For General-Purpose Switching Applications
- High Conductance
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **The BAV70Q is suitable for automotive applications requiring specific change control; this part is AEC-Q101 qualified, PPAP capable, and manufactured in IATF 16949 certified facilities.**

<https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Package: SOT23
- Package Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Alloy 42 Leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208 (e3)
- Polarity: See Diagram
- Weight: 0.008 grams (Approximate)

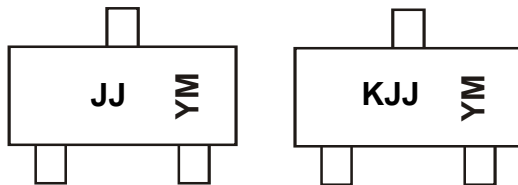


Ordering Information (Notes 4 & 5)

Orderable Part Number	Package	Packing	
		Qty.	Carrier
BAV70-7-F	SOT23	3000	Tape & Reel
BAV70-13-F	SOT23	10,000	Tape & Reel
BAV70Q-7-F	SOT23	3000	Tape & Reel
BAV70Q-13-F	SOT23	10,000	Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.
 5. Products manufactured with Date Code W9 (week 39, 2009) and newer are built with Green Molding Compound. Products manufactured prior to Date Code W9 are built with Non-Green Molding Compound and may contain Halogens or Sb₂O₃ Fire Retardants.

Marking Information



JJ or KJJ = Product Type Marking Code
 YM = Date Code Marking
 Y = Year (ex: L = 2024)
 M = Month (ex: N = November)
 A Bar around the Date Code Marking Denotes Assembly Site

Date Code Key

Year	2000	-	2024	2025	2026	2027	2028	2029	2030	2031	2032	2033
Code	L	-	L	M	N	P	R	S	T	U	V	W

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Non-Repetitive Peak Reverse Voltage	V _{RM}	100	V
Peak Repetitive Reverse Voltage	V _{RRM}	75	V
Working Peak Reverse Voltage	V _{RWM}		
DC Blocking Voltage	V _R		
Forward Continuous Current (Note 6)	I _{FM}	300	mA
Repetitive Peak Forward Current	I _{FRM}	450	mA
Non-Repetitive Peak Forward Surge Current	I _{FSM}	@ t = 1.0μs	2.0
		@ t = 1.0s	1.0

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P _D	350	mW
Thermal Resistance Junction to Ambient Air (Note 6)	R _{θJA}	357	°C/W
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	V _{(BR)R}	75	—	V	I _R = 2.5μA
Forward Voltage	V _F	—	0.715	V	I _F = 1.0mA
			0.855		I _F = 10mA
			1.0		I _F = 50mA
			1.25		I _F = 150mA
Reverse Current (Note 7)	I _R	—	2.5	μA	V _R = 75V
			50	μA	V _R = 75V, T _J = +150°C
			30	μA	V _R = 25V, T _J = +150°C
			25	nA	V _R = 20V
Total Capacitance	C _T	—	2.0	pF	V _R = 0V, f = 1.0MHz
Reverse-Recovery Time	t _{rr}	—	4.0	ns	I _F = I _R = 10mA, I _{rr} = 0.1 × I _R , R _L = 100Ω

Notes: 6. Part mounted on FR-4 board with 1 inch square, 2oz copper pad layout.
7. Short duration pulse test used to minimize self-heating effect.

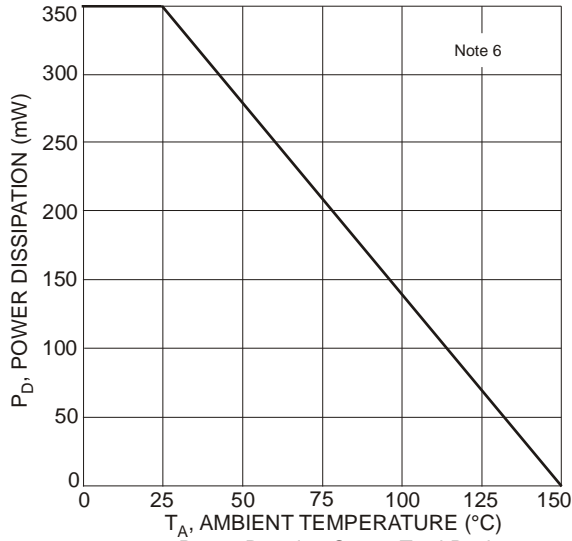


Figure 1. Power Derating Curve, Total Package

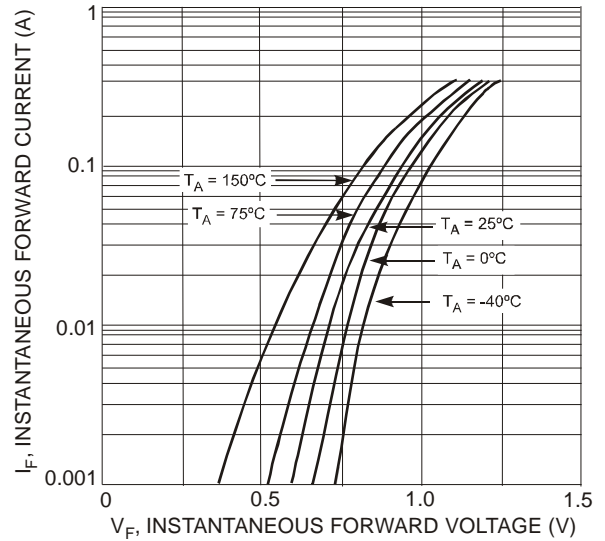


Figure 2. Typical Forward Characteristics, Per Element

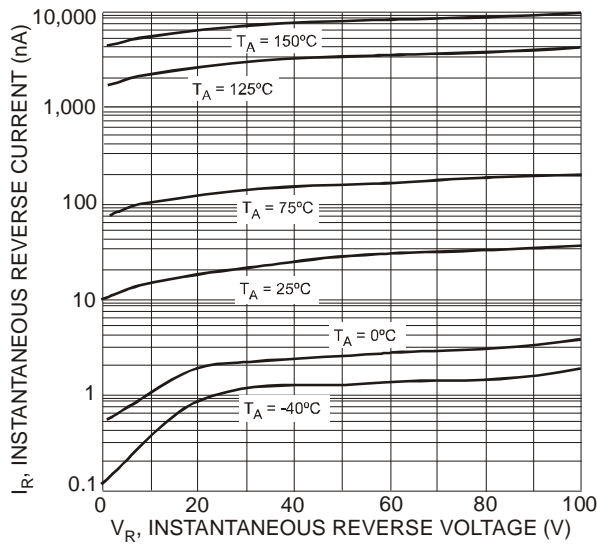


Figure 3. Typical Reverse Characteristics, Per Element

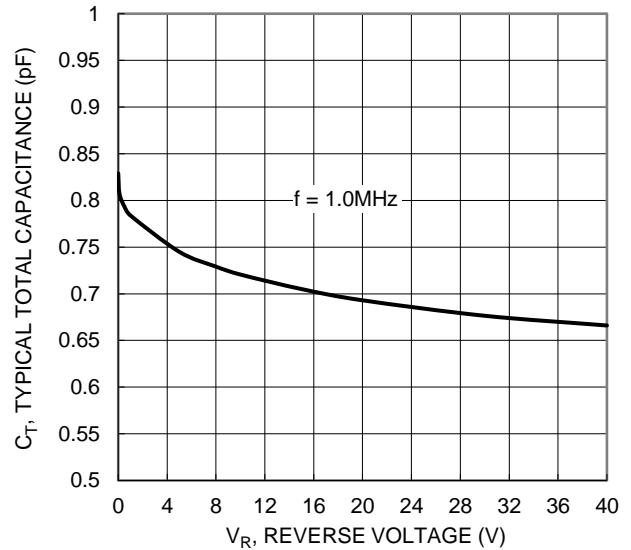


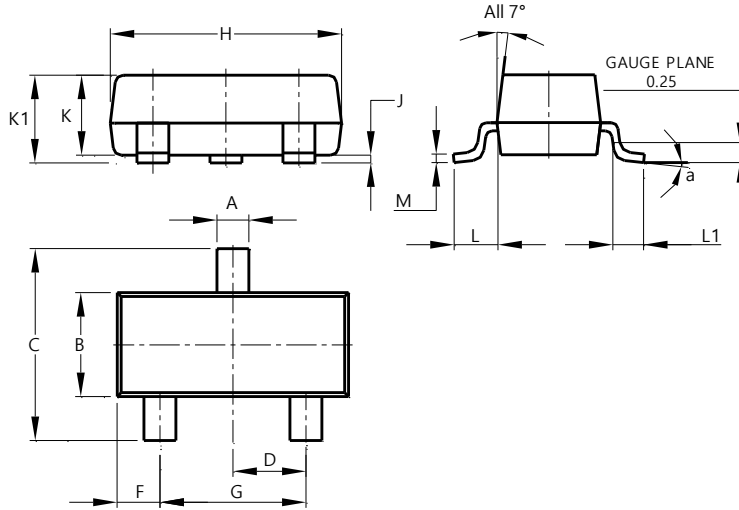
Figure 4. Typical Total Capacitance, Per Element

Note: 6. Part mounted on FR-4 board with 1 inch square, 2oz copper pad layout.

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23



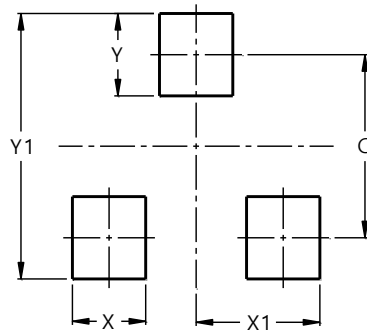
SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	0°	8°	--

All Dimensions in mm

Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SOT23



Dimensions	Value (in mm)
C	2.0
X	0.8
X1	1.35
Y	0.9
Y1	2.9

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